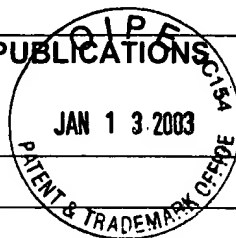


U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)		Docket No. APPM/5619	Serial No. 09/912,103
SUPPLEMENTAL LIST OF PATENTS AND PUBLICATIONS CITED BY APPLICANT		Applicant Nguyen, et al.	Confirmation No.: 4476
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Examiner K. Nguyen			

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*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
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KN	A2	6,312,616	11/06/2001	Chinn, et al.	216	68	12/03/1998
KN	A3	6,277,763	08/21/2001	Kugimiyama, et al.	438	720	12/16/1999
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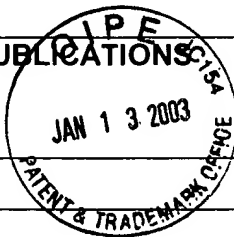
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		Nguyen, et al.	4476
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**Foreign Patent Documents**

*Examiner Initial		Document Number	Date	Country	Class	Subclass	Translation	
							YES	NO
KN	B1	27 01 458 A1	07/21/1977	DE	G03C	5/48	<input type="checkbox"/>	<input checked="" type="checkbox"/>
KN	B2	0 552 491 A1	07/28/1993	EP	H01J	37/32	<input type="checkbox"/>	<input type="checkbox"/>
KN	B3	0 489 407 A2	06/10/1992	EP	H01J	37/32	<input type="checkbox"/>	<input type="checkbox"/>
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	B 24						<input checked="" type="checkbox"/>	<input type="checkbox"/>

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OTHER ART

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KW	C2	Pan, et al., "Selective reactive ion etching of tungsten films in CHF ₃ and other fluorinated gases", <i>J. Vac. Sci. and Tech. B</i> , 6(4), (July/August 1988), pp. 1073-1080
KW	C3	Theisen, et al., "Maskless Tungsten Etch Process for Plug Fill", <i>1046b Extended Abstracts</i> , Electrochem Soc., Spring Meeting, 90(1) (May 6-11, 1990), pp. 248-249
KW	C4	Ootera, et al., "Highly Selective Etching of W/WN/Poly-Si Gate on Thin Oxide Film With Gaspuff Plasmas", <i>Proc. of Symp. on Dry Process</i> (Nov. 11-12, 1999), pp. 155-160
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KW	C6	Kaplita, et al., "Polysilicon planarization and plug recess etching in decoupled plasma source chamber using two endpoint techniques", <i>The SPIE Conf. on Process, Equipment & Materials Control</i> , Vol. 3882 (Sept. 1999), pp. 90-97
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	C8	
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